

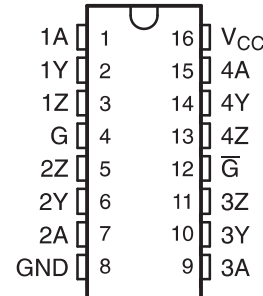
## FEATURES

- **Controlled Baseline**
  - One Assembly
  - One Test Site
  - One Fabrication Site
- **Extended Temperature Performance of –55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree <sup>(1)</sup>**
- **Meets or Exceeds the Requirements of TIA/EIA-422-B and ITU Recommendation V.11**
- **Low Power,  $I_{CC} = 100 \mu\text{A}$  Typ**
- **Operates From a Single 5 V Supply**
- **High Speed,  $t_{PLH} = t_{PHL} = 7 \text{ ns}$  Typ**
- **Low Pulse Distortion,  $t_{sk(p)} = 0.5 \text{ ns}$  Typ**

- (1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- **High Output Impedance in Power-Off Conditions**
- **Improved Replacement for AM26LS31**

AM26C31... D PACKAGE



## DESCRIPTION/ORDERING INFORMATION

The AM26C31 is a differential line driver with complementary outputs, designed to meet the requirements of TIA/EIA -422-B and ITU (formerly CCITT). The 3-state outputs have high-current capability for driving balanced lines, such as twisted-pair or parallel-wire transmission lines, and they provide the high-impedance state in the power-off condition. The enable functions are common to all four drivers and offer the choice of an active-high (G) or active-low ( $\bar{G}$ ) enable input. BiCMOS circuitry reduces power consumption without sacrificing speed.

The AM26C31 is characterized for operation over extended temperature range of –55°C to 125°C.

### ORDERING INFORMATION<sup>(1)</sup>

T <sub>A</sub>	PACKAGE <sup>(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	SOIC – D	Reel of 2500	AM26C31MDREP	26C31EP

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at [www.ti.com](http://www.ti.com).
- (2) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).

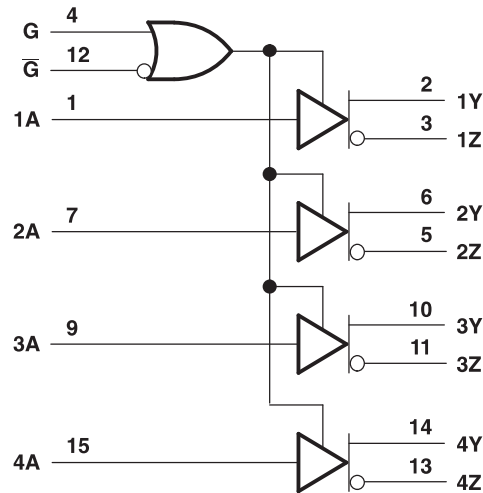


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

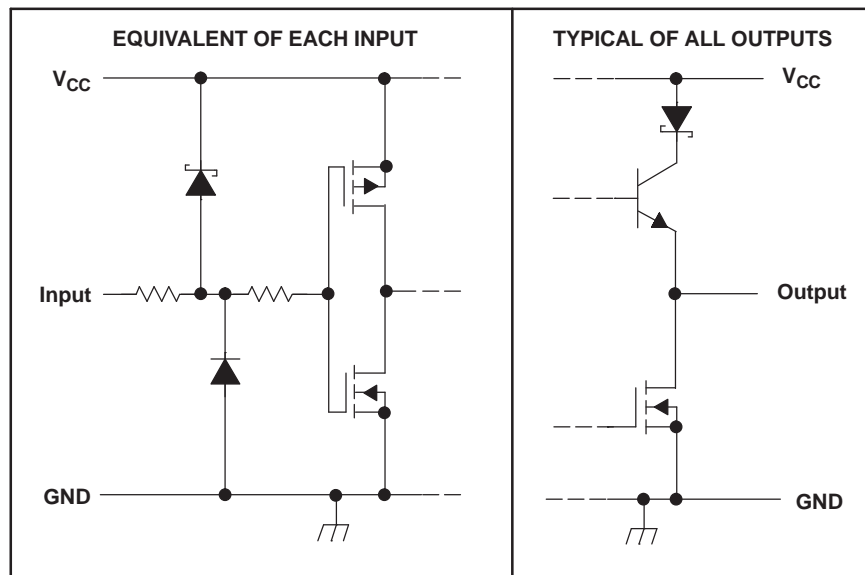
FUNCTION TABLE  
 (each driver)

INPUT A	ENABLES		OUTPUT	
	G	$\bar{G}$	Y	Z
H	H	X	H	L
L	H	X	L	H
H	X	L	H	L
L	X	L	L	H
X	L	H	Z	Z

LOGIC DIAGRAM (POSITIVE LOGIC)



SCHEMATICS OF INPUTS AND OUTPUTS



**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range <sup>(2)</sup>	-0.5	7	V
$V_I$	Input voltage range	-0.5	$V_{CC} + 0.5$	V
$V_{ID}$	Differential input voltage range	-14	14	V
$V_O$	Output voltage range	-0.5	7	V
$I_{IK}$ or $I_{OK}$	Input or output clamp current		±20	mA
$I_O$	Output current		±150	mA
	$V_{CC}$ current		200	mA
	GND current		-200	mA
$\theta_{JA}$	Package thermal impedance <sup>(3)(4)</sup>		73	°C/W
$T_J$	Operating virtual junction temperature		150	°C
$T_{stg}$	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential output voltage ( $V_{OD}$ ), are with respect to the network ground terminal.
- (3) Maximum power dissipation is a function of  $T_J(\max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(\max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

**RECOMMENDED OPERATING CONDITIONS**

		MIN	NOM	MAX	UNIT
$V_{CC}$	Supply voltage	4.5	5	5.5	V
$V_{ID}$	Differential input voltage		±7		V
$V_{IH}$	High-level input voltage	2			V
$V_{IL}$	Low-level input voltage			0.8	V
$I_{OH}$	High-level output current			-20	mA
$I_{OL}$	Low-level output current			20	mA
$T_A$	Operating free-air temperature	-55		125	°C

## ELECTRICAL CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>	High-level output voltage	I <sub>O</sub> = -20 mA	2.2	3.4		V
V <sub>OL</sub>	Low-level output voltage	I <sub>O</sub> = 20 mA		0.2	0.4	V
V <sub>OD</sub>	Differential output voltage magnitude	R <sub>L</sub> = 100 Ω, See Figure 1	2	3.1		V
Δ V <sub>OD</sub>	Change in magnitude of differential output voltage <sup>(2)</sup>	R <sub>L</sub> = 100 Ω, See Figure 1			±0.4	V
V <sub>OC</sub>	Common-mode output voltage	R <sub>L</sub> = 100 Ω, See Figure 1			3	V
Δ V <sub>OC</sub>	Change in magnitude of common-mode output voltage <sup>(2)</sup>	R <sub>L</sub> = 100 Ω, See Figure 1			±0.4	V
I <sub>I</sub>	Input current	V <sub>I</sub> = V <sub>CC</sub> or GND			±1	μA
I <sub>O(off)</sub>	Driver output current with power off	V <sub>CC</sub> = 0			100	μA
		V <sub>O</sub> = 6 V				
		V <sub>O</sub> = -0.25 V			-100	
I <sub>OS</sub>	Driver output short-circuit current	V <sub>O</sub> = 0			-170	mA
I <sub>OZ</sub>	High-impedance off-state output current	V <sub>O</sub> = 2.5 V			20	μA
		V <sub>O</sub> = 0.5 V			-20	
I <sub>CC</sub>	Quiescent supply current	I <sub>O</sub> = 0			100	μA
		V <sub>I</sub> = 0 V or 5 V				
		I <sub>O</sub> = 0			3.2	mA
		V <sub>I</sub> = 2.4 V or 0.5 V <sup>(3)</sup>				
C <sub>I</sub>	Input capacitance			6		pF

(1) All typical values are at V<sub>CC</sub> = 5 V and T<sub>A</sub> = 25°C.

(2) Δ|V<sub>OD</sub>| and Δ|V<sub>OC</sub>| are the changes in magnitude of V<sub>OD</sub> and V<sub>OC</sub>, respectively, that occur when the input is changed from a high level to a low level.

(3) This parameter is measured per input. All other inputs are at 0 V or 5 V.

## SWITCHING CHARACTERISTICS

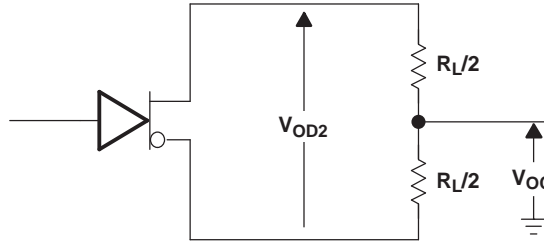
over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
t <sub>PLH</sub>	Propagation delay time, low- to high-level output	S1 is open, See Figure 2		7	12	ns
t <sub>PHL</sub>	Propagation delay time, high- to low-level output	S1 is open, See Figure 2		6.5	12	ns
t <sub>sk(p)</sub>	Pulse skew time ( t <sub>PLH</sub> - t <sub>PHL</sub>  )	S1 is open, See Figure 2		0.5	4	ns
t <sub>r(OD)</sub> , t <sub>f(OD)</sub>	Differential output rise and fall times	S1 is open, See Figure 3		5	12	ns
t <sub>PZH</sub>	Output enable time to high level	S1 is closed, See Figure 4		10	19	ns
t <sub>PZL</sub>	Output enable time to low level	S1 is closed, See Figure 4		10	19	ns
t <sub>PHZ</sub>	Output disable time from high level	S1 is closed, See Figure 4		7	16	ns
t <sub>PLZ</sub>	Output disable time from low level	S1 is closed, See Figure 4		7	16	ns
C <sub>pd</sub>	Power dissipation capacitance (each driver) <sup>(2)</sup>	S1 is open, See Figure 2		100		pF

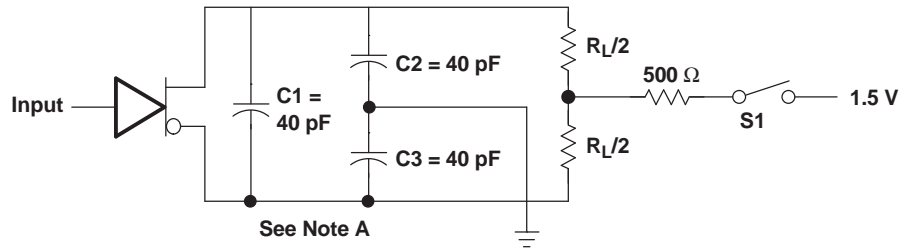
(1) All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

(2) C<sub>pd</sub> is used to estimate the switching losses according to P<sub>D</sub> = C<sub>pd</sub> × V<sub>CC</sub><sup>2</sup> × f, where f is the switching frequency.

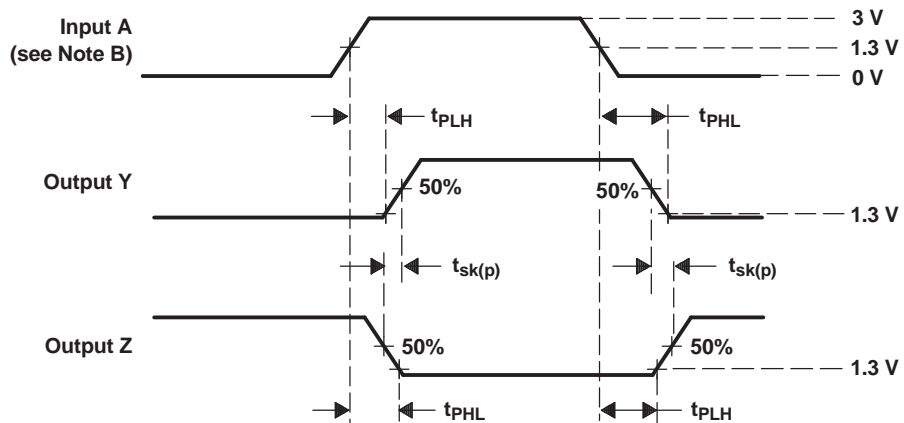
**PARAMETER MEASUREMENT INFORMATION**



**Figure 1. Differential and Common-Mode Output Voltages**



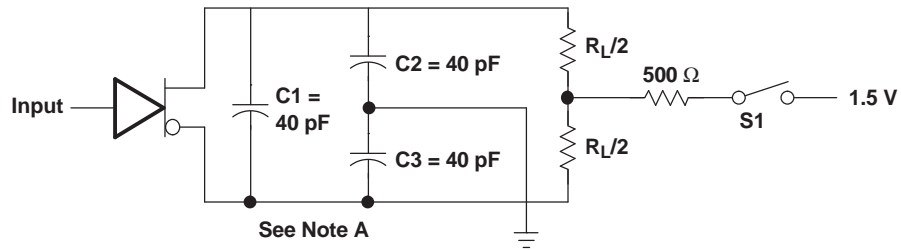
**TEST CIRCUIT**



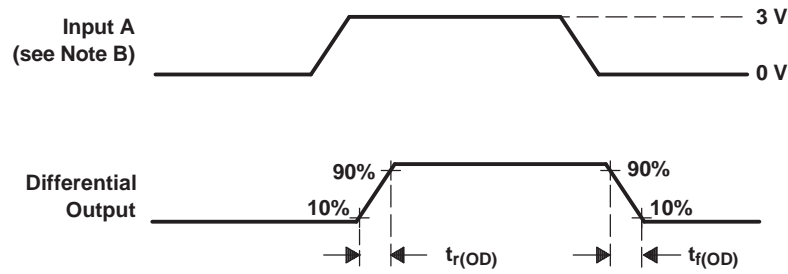
- A.  $C_1$ ,  $C_2$ , and  $C_3$  include probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ , duty cycle  $\leq 50\%$ , and  $t_r, t_f \leq 6 \text{ ns}$ .

**Figure 2. Propagation Delay Time and Skew Waveforms and Test Circuit**

PARAMETER MEASUREMENT INFORMATION (continued)



TEST CIRCUIT

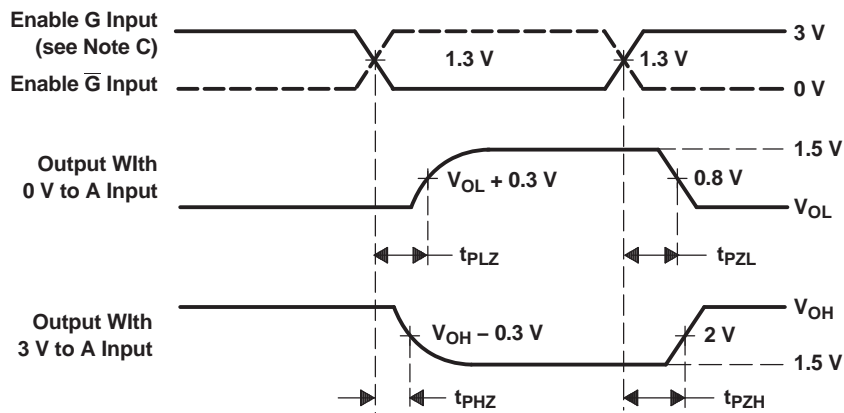
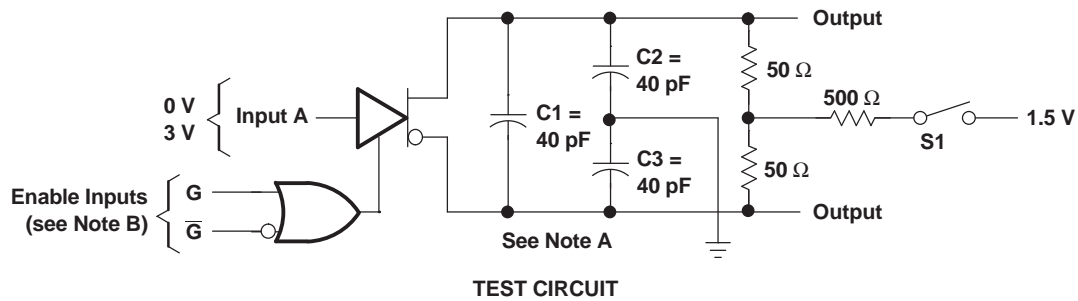


VOLTAGE WAVEFORMS

- A. C1, C2, and C3 include probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, duty cycle  $\leq$  50%, and  $t_r, t_f \leq$  6 ns.

Figure 3. Differential Output Rise and Fall Time Waveforms and Test Circuit

PARAMETER MEASUREMENT INFORMATION (continued)



VOLTAGE WAVEFORMS

- A. C1, C2, and C3 include probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, duty cycle  $\leq$  50%,  $t_r <$  6 ns, and  $t_f <$  6 ns.
- C. Each enable is tested separately.

Figure 4. Output Enable and Disable Time Waveforms and Test Circuit

### TYPICAL CHARACTERISTICS

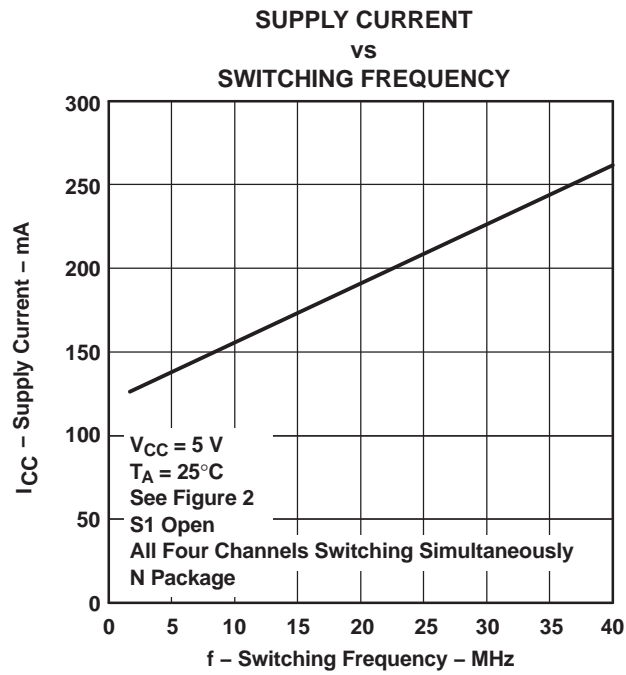


Figure 5.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
AM26C31MDREP	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	26C31EP	<a href="#">Samples</a>
V62/07647-01XE	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	26C31EP	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF AM26C31-EP :**

- Catalog: [AM26C31](#)

- Military: [AM26C31M](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)